



·			<del></del>	Time stamp
L Number	Hits	Search Text	DB USPAT;	2003/01/30 15:08
-	6039	(integrated adj circuit) and (contact adj	US-PGPUB;	
7	1	pad) and (under adj bump adj region or	EPO; JPO;	
		layer)	DERWENT	1
	o	(integrated adj circuit) and (contact adj	USPAT;	2003/01/30 15:10
-	U	nad) and (under adi bump adi region or	US-PGPUB;	
ļ		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adi homds)	DERWENT	2003/01/30 15:15
_	184	(integrated add circuit) and (contact or	USPAT;	2003/01/30 15:15
·		output/input adi pads) and (under ad) bump	US-PGPUB; EPO; JPO;	
1		adj region or layer) and (solder adj	DERWENT	
		bonds) and (wire adj bonds)	USPAT;	2003/01/31 10:15
-	118	(integrated adj circuit) and (contact adj	US-PGPUB;	
		pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire	EPO; JPO;	i
		layer) and (solder ad) bolids) and (will	DERWENT	j
	110	adj bonds) (integrated adj circuit) and (contact adj	USPAT;	2003/01/31 10:25
-	118	pad) and (under adj bump adj region or	US-PGPUB;	
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adi honds) and (barrier adj region or	DERWENT	
	1	layer) and (passivation adj region or	ı	
		layer)		2003/01/31 11:45
_	0	1 (1	USPAT;	2003/01/31 11:43
			US-PGPUB; EPO; JPO;	
			DERWENT	
	1		USPAT;	2003/01/31 11:45
_	0	"09888674" and (barrier)	US-PGPUB;	
			EPO; JPO;	
			DERWENT	1
		"09/888674" and (barrier)	USPAT;	2003/01/31 11:45
-	0	"09/888874 and (balliol)	US-PGPUB;	ļ
			EPO; JPO;	
			DERWENT	2003/01/31 12:17
<b> </b> _	118	(integrated adj circuit) and (contact adj	USPAT;	2003/01/31 12.17
		nad) and (under adj bump adj region or	US-PGPUB;	
		layer) and (solder adj bonds) and (wire	EPO; JPO; DERWENT	
1	1	adj bonds) and (barrier adj region or	DEKWENT	
	1	layer) and (passivation adj region or		
ļ		layer) (integrated adj circuit) and (contact adj	USPAT;	2003/01/31 12:24
-	0	pad) and ((under adj bump adj metallurgy)	US-PGPUB;	
1		or ubm) and (solder adj bonds) and (wire	EPO; JPO;	ļ
		and (barrier) and (passivation)	DERWENT	
		(contact adj	USPAT;	2003/01/31 12:25
-		land) and ((under adi bump adl metallurgy)	US-PGPUB;	
1	1	or ubm) and (solder adj bonds) and (wire	EPO; JPO;	
	1	ladi bonds) and (barrier)	DERWENT	2003/01/31 12:26
-	4	[ /integrated add circuit) and (contact ad]	USPAT; US-PGPUB;	2003/01/31 12:20
		nad) and ((under adi bump ad] metallurgy)	EPO; JPO;	
		or ubm) and (solder) and (wire adj bonds)	DERWENT	
		and (barrier)	USPAT;	2003/02/01 15:10
-	28	(integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy)	US-PGPUB;	
		or ubm) and (solder) and (wire) and	EPO; JPO;	
		or ubm) and (solder) and (wire, and (barrier)	DERWENT	
	111	oldintegrated adj circuit) and (contact ad)	USPAT;	2003/01/31 15:38
-	118	had and (under adj bump adj region of	US-PGPUB;	
		layer) and (solder adl bonds) and (wife	EPO; JPO;	
1		ladi bonds) and (barrier ad) region or	DERWENT	
		layer) and (passivation adj region or		
		lawar)	HCDAM.	2003/02/01 15:01
-	2	2   /integrated adj circuit) and (contact ad)	USPAT; US-PGPUB;	2003/02/01 13:01
		nad) and ((under ad) bump ad) metallurgy)	EPO; JPO;	
		or ubm) and (solder) and (wire) and	DERWENT	
į	1	(barrier) and (lead)	USPAT;	2003/02/01 15:13
-		0 438/15.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump		
		and (contact ad) pad) and (tinder ad) bamp adj metallurgy) or ubm) and (solder) and	EPO; JPO;	
		(wire) and (barrier)	DERWENT	
	·	(MITE) and (Darrier)		

4.			
-	438/15,762,763.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/737.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/01 15:15